

In the Claims:Please replace claim 1 with the following:

1. An apparatus for separating individual circuit boards from a multiple board array with pre-scored planes and a plurality of electrical components comprising:

A at least one splitting element positioned along one of the pre-scored planes; and

at least one torque inducing element using edge loading to mechanically force the multiple board array onto said at least one splitting element and thereby breaking the multiple board array along the pre-scored plane said at least one torque inducing element forcing the multiple board array without loading the plurality of electrical components.

Please replace claim 3 with the following:

3. An apparatus as described in claim 2 wherein said stabilizing element includes a plate element; and

AJ a plurality of spring elements, said plurality of spring elements pushing said plate element onto the multiple board array.

Please replace claim 9 with the following:

9. An apparatus for separating individual circuit board from a multiple board array with pre-scored planes and a plurality of electrical components comprising:

A3 at least one splitting element positioned along one of the pre-scored planes; and

at least one torque inducing element using surface loading to mechanically force the multiple board array onto said at least one splitting element and thereby breaking the multiple board array along the pre-scored plane said at least one torque inducing element forcing the multiple board array without loading the plurality of electrical components; and

a transport element for automatically positioning said at least one splitting element along one of the pre-scored planes.

Please replace claim 11 with the following:

11. An apparatus as described in claim 10 wherein said stabilizing element includes a plate element; and
A4 a plurality of spring elements, said plurality of spring elements pushing said plate element onto the multiple board array.

Please replace claim 16 with the following:

16. A method for separating individual circuit boards from a multiple board array with pre-scored planes comprising:
A5 positioning a splitting element along one of the pre-scored planes, and inducing torque on the multiple board array such that the multiple board array is forced onto the splitting element and breaks along the pre-scored plane.

Please add new claim 20 as follows:

20. An apparatus as described in claim 9 wherein said torque inducing element applies said surface loading to the multiple board array by way of a shield element attached to the multiple board array such that the plurality of electrical components remain undamaged.

Please add new claim 21 as follows:

21. A method as described in claim 16 wherein said inducing torque on the multiple board array includes transferring load from a torque inducing element through a shield element into the multiple board array.